

Title (en)

METHOD FOR PRODUCING AN OPTOELECTRONIC SEMICONDUCTOR COMPONENT

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES OPTOELEKTRONISCHEN HALBLEITERBAUELEMENTS

Title (fr)

PROCÉDÉ DE FABRICATION D'UN COMPOSANT SEMI-CONDUCTEUR OPTOÉLECTRONIQUE

Publication

EP 2614538 A1 20130717 (DE)

Application

EP 11754342 A 20110829

Priority

- DE 102010044560 A 20100907
- EP 2011064836 W 20110829

Abstract (en)

[origin: WO2012031932A1] The invention relates to a method for producing an optoelectronic semiconductor component, wherein electric contacts of the subsequent optoelectronic semiconductor component are prevented from contacting foreign particles of a filler.

IPC 8 full level

H01L 33/62 (2010.01); **H01L 25/16** (2006.01); **H01L 33/50** (2010.01); **H01L 33/56** (2010.01); **H01L 33/60** (2010.01)

CPC (source: EP KR US)

H01L 24/18 (2013.01 - US); **H01L 24/24** (2013.01 - EP US); **H01L 24/82** (2013.01 - EP US); **H01L 25/16** (2013.01 - KR); **H01L 27/15** (2013.01 - KR); **H01L 33/48** (2013.01 - KR); **H01L 33/50** (2013.01 - KR); **H01L 33/56** (2013.01 - EP US); **H01L 33/62** (2013.01 - EP US); **H01L 25/167** (2013.01 - EP US); **H01L 33/50** (2013.01 - EP US); **H01L 33/58** (2013.01 - EP US); **H01L 33/60** (2013.01 - EP US); **H01L 2224/18** (2013.01 - US); **H01L 2224/24137** (2013.01 - EP US); **H01L 2224/32225** (2013.01 - EP US); **H01L 2224/32245** (2013.01 - EP US); **H01L 2224/73267** (2013.01 - EP US); **H01L 2224/92244** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01023** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/12041** (2013.01 - EP US); **H01L 2924/12042** (2013.01 - EP US); **H01L 2933/0066** (2013.01 - EP US); **H01L 2933/0091** (2013.01 - EP US)

Citation (search report)

See references of WO 2012031932A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

DE 102010044560 A1 20120308; CN 103098248 A 20130508; CN 103098248 B 20160120; EP 2614538 A1 20130717; JP 2013539604 A 20131024; JP 5639271 B2 20141210; KR 101457827 B1 20141104; KR 20130079530 A 20130710; US 2014131739 A1 20140515; US 9224931 B2 20151229; WO 2012031932 A1 20120315

DOCDB simple family (application)

DE 102010044560 A 20100907; CN 201180043207 A 20110829; EP 11754342 A 20110829; EP 2011064836 W 20110829; JP 2013527542 A 20110829; KR 20137008785 A 20110829; US 201113820773 A 20110829